

[c1](canceled)

A package and method for packaging opto-electric devices, comprising:

- a generally rectangular package body comprising four sidewalls;
- one or more than one thermal electrical cooler;
- one or more than one platform on which opto-electronic devices and components to be disposed;
- attaching the said thermal electrical cooler(s) on the sidewall(s) of the package box by applying epoxy or solder;
- attaching the side(s) of the said platform(s) to the top of the thermal electrical coolers.

[c2](canceled)

The package and method of claim 1, wherein the package body has one or more than optical connector on its sidewall(s).

[c3](canceled)

The package and method of claim 1, wherein the package body has a top defining a generally rectangular opening and a closed bottom.

[c4](canceled)

The package body of claim 3 further comprising a lid hermetically sealed to the top of the package, the lid being free of connectors, leads, and mounting tabs.

[c5](canceled)

The package and method of claim 1, wherein the package box defining one generally rectangular top opening and another generally rectangular bottom opening.

[c6](canceled)

The package body of claim 5 further comprising a top lid and a bottom lid hermetically sealed to the top and the bottom of the box, the top and bottom lids being free of connectors, leads, and mounting tabs.

[c7](canceled)

The package and method of claim 1, wherein the package box is dual in-line package, in which a plurality of electronic leads extend the bottom of the said package.

[c8](canceled)

The package and method of claim 1, wherein the package box is butterfly box, in which a plurality of electronic leads extend one or more than one sidewall of the said package.

[c9](canceled)

The package and method of claim 1, wherein the thermal electrical cooler has a top plate and bottom plate and semiconductor elements sandwiched between the said top and bottom plates.

[c10](canceled)

The package and method of claim 1, wherein the package body has no or one or more than one radio-frequency connector on its sidewall(s) for high frequency connection to or from the component(s) inside the box.

[c11](new)

A package for packaging opto-electric devices, comprising:

a generally rectangular package box comprising four sidewalls, one of said sidewalls having an optical connector;

a generally rectangular platform on which opto-electronic devices and a plurality of optical components to be disposed, which having means for attachment of two sides of said platform to two of said sidewalls;

attachment means for moving vertically and tilting said platform relative to said sidewalls to align said opto-electronic devices to said optical connector optically with the lateral movement of said opto-electronic devices and said optical components on the top of said platform and then securing said platform to said package box by one of solder, epoxy, or welder;

[c12](new)

The package of claim 1 further comprising two thermal electrical coolers, each comprising a cold junction side and a hot junction side and first having means for fixing of said hot junction side to one surface of said sidewalls and having means for attachment of said cold junction side to one side of said platform;

Whereby said thermal electrical coolers separate said platform from said package box thermally and duct extracted heat from said platform to said package box for transfer out of said package box.

[c13](new)

The package of claim 1 further comprising a lid sealed to the top of said package box, the lid being free of connectors, leads, and mounting tabs.

[c14](new)

The package of claim 1 further comprising a base, which having means for being secured to the bottom of said package box.